

Dual P-Channel 20-V (D-S) MOSFET

CHARACTERISTICS

- P-Channel Vertical DMOS
- Macro Model (Subcircuit Model)
- Level 3 MOS

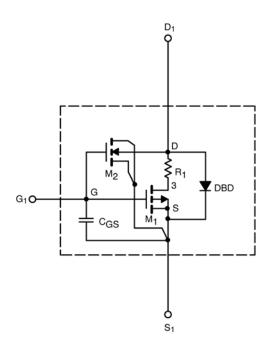
- Apply for both Linear and Switching Application
- Accurate over the -55 to 125°C Temperature Range
- Model the Gate Charge, Transient, and Diode Reverse Recovery Characteristics

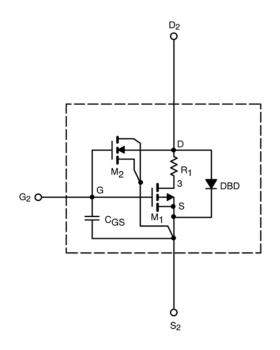
DESCRIPTION

The attached spice model describes the typical electrical characteristics of the p-channel vertical DMOS. The subcircuit model is extracted and optimized over the -55 to 125° C temperature ranges under the pulsed 0-V to 5-V gate drive. The saturated output impedance is best fit at the gate bias near the threshold voltage.

A novel gate-to-drain feedback capacitance network is used to model the gate charge characteristics while avoiding convergence difficulties of the switched C_{gd} model. All model parameter values are optimized to provide a best fit to the measured electrical data and are not intended as an exact physical interpretation of the device.

SUBCIRCUIT MODEL SCHEMATIC





This document is intended as a SPICE modeling guideline and does not constitute a commercial product data sheet. Designers should refer to the appropriate data sheet of the same number for guaranteed specification limits.



Parameter	Symbol	Test Condition	Simulated Data	Measured Data	Unit
Static	•		•		
Gate Threshold Voltage	V _{GS(th)}	$V_{\text{DS}} = V_{\text{GS}}, \ I_{\text{D}} = -500 \ \mu\text{A}$	0.75		V
On-State Drain Current ^a	I _{D(on)}	V_{DS} = -5 V, V_{GS} = -4.5 V	235		А
Drain-Source On-State Resistance ^a	۲ _{DS(on)}	V_{GS} = -4.5 V, I _D = -9.4 A	0.0124	0.0125	Ω
		V_{GS} = -2.5 V, I _D = -8.4 A	0.015	0.0155	
		V_{GS} = -1.8 V, I _D = -5 A	0.019	0.020	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -9.4 \text{ A}$	42	40	S
Diode Forward Voltage ^a	V _{SD}	$I_{\rm S}$ = -1.7 A, $V_{\rm GS}$ = 0 V	-0.80	-0.70	V
Dynamic ^b			•		
Total Gate Charge	Qg	V_{DS} = -6 V, V_{GS} = -4.5 V, I _D = -9.4 A	47	43	nC
Gate-Source Charge	Q _{gs}		7.1	7.1	
Gate-Drain Charge	Q _{gd}		10.9	10.9	
Turn-On Delay Time	t _{d(on)}	V_{DD} = -6 V, R _L = 6 Ω $I_D \cong$ -1 A, V _{GEN} = -4.5 V, R _G = 6 Ω I_F = -1.7 A, di/dt = 100 A/µs	36	32	ns
Rise Time	tr		35	42	
Turn-Off Delay Time	t _{d(off)}		166	350	
Fall Time	t _f		43	160	
Source-Drain Reverse Recovery Time	t _{rr}		135	127	

Notes

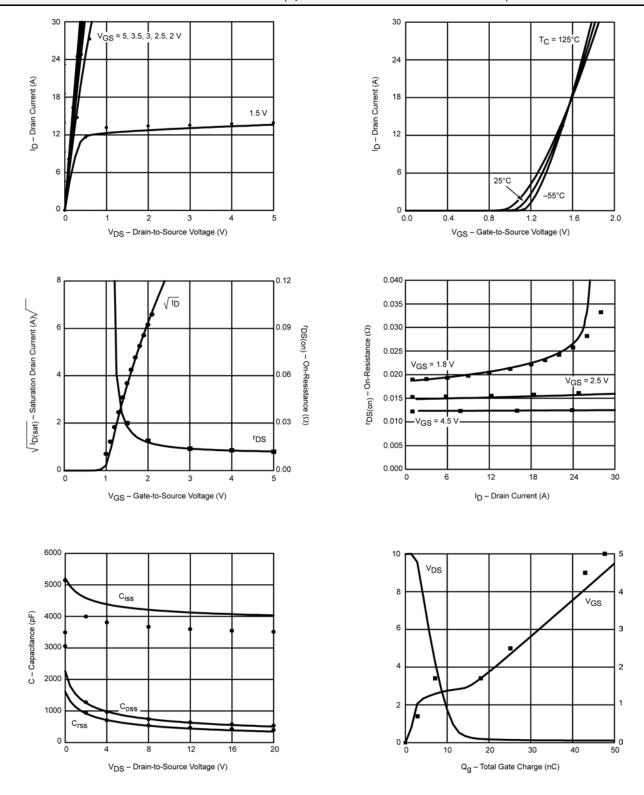
a. Pulse test; pulse width \leq 300 μs , duty cycle \leq 2%. b. Guaranteed by design, not subject to production testing.



SPICE Device Model Si4913DY

Vishay Siliconix

COMPARISON OF MODEL WITH MEASURED DATA (TJ=25°C UNLESS OTHERWISE NOTED)



Note: Dots and squares represent measured data.



Vishay

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